

**IN THE CLAIMS:**

1. (Currently Amended): A photoresist composition comprising a polymeric binder, a photoactive component, an organic acid selected from the group consisting of a sulfonic acid, a phosphonic acid, formic acid, acetic acid, propionic acid, oxalic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, lactic acid, tartaric acid, malic acid, phthalic acid, benzene tricarboxylic acid, salicylic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid and sebacic acid and optionally a cross-linking agent, wherein the organic acid is non-polymerizable with the polymeric binder, optional cross-linking agent or both, and is present in an amount of from 0.5 to 5 parts per 40 parts of polymeric binder on a dry weight basis.

2. (Currently Amended): The composition of claim 1 wherein the organic acid is selected from the group consisting of carboxylic acids and ~~a sulfonic acids~~ acid, formic acid, acetic acid, propionic acid, oxalic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, lactic acid, tartaric acid, malic acid, phthalic acid, benzene tricarboxylic acid, salicylic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid and sebacic acid.

3. (Cancelled).

4. (Cancelled).

5. (Currently Amended): The composition of claim ~~[[4]]~~ 2 wherein the organic acid is selected from the group consisting of acetic acid, propionic acid, malonic acid, succinic acid, glutaric

acid, adipic acid, glycolic acid, lactic acid, tartaric acid, citric acid, malic acid, phthalic acid, benzene tricarboxylic acid, salicylic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid and sebacic acid.

6. (Original): The composition of claim 1 wherein the photoresist is negative-acting.

7. (Previously Presented): The composition of claim 1 wherein the photoactive component is selected from the group consisting of 9-phenylacridine, n-phenylglycine, benzophenone, N,N'-tetramethyl-4,4'-diaminobenzophenone, N,N'-tetraethyl-4,4'-diaminobenzophenone, 4-methoxy-4'-dimethylaminobenzophenone, 3,3'-dimethyl-4-methoxybenzophenone, p,p'-bis(dimethylamino)benzophenone, p,p'-bis(diethylamino)-benzophenone, anthraquinone, 2-ethylanthraquinone, naphthaquinone, phenanthraquinone, benzoin, benzoinmethylether, benzoinethylether, benzoinisopropylether, benzoin-n-butylether, benzoin-phenylether, methylbenzoin, ethylbenzoin, dibenzyl, benzyldiphenyldisulfide, benzyldimethylketal, 1,7-bis(9-acridinyl)heptane, 2-chlorothioxanthone, 2-methylthioxanthone, 2,4-diethylthioxanthone, 2,4-dimethylthioxanthone, 2-isopropylthioxanthone, 1,1-dichloroacetophenone, p-t-butyl-dichloroacetophenone, 2,2-diethoxyacetophenone, 2,2-dimethoxy-2-phenylacetophenone, 2,2-dichloro-4-phenoxyacetophenone, 2-(o-chlorophenyl)-4,5-diphenylimidazole dimer, 2-(o-chlorophenyl)-4,5-di(m-methoxyphenyl)imidazole dimer, 2-(o-fluorophenyl)-4,5-diphenylimidazole dimer, 2-(o-methoxyphenyl)-4,5-diphenylimidazole dimer, 2-(p-methoxyphenyl)-4,5-diphenylimidazole dimer, 2,4-di(p-methoxyphenyl)-5-phenylimidazole dimer, 2-(2,4-dimethoxyphenyl)-4,5-diphenylimidazole dimer and 2-(p-methylmercaptophenyl)-4,5-diphenylimidazole dimer.

8. (Previously Presented): The composition of claim 1 wherein the polymeric binder comprises sufficient acid functionality to render said photoresist composition developable in alkaline aqueous solution.

9. (Original): The composition of claim 8 wherein the polymeric binder has an acid number of from about 50 to about 250.

10. (Previously Presented): The composition of claim 1 wherein the organic acid is present in an amount up to 10 wt %, based on the total dry weight of the polymeric binder.

11. (Previously Presented): The composition of claim 10 wherein the organic acid is present in an amount up to 8 wt %, based on the total dry weight of the polymeric binder.

12. (Currently Amended): A method of enhancing the removal of a photoresist composition from a substrate comprising the step of combining an organic acid selected from the group consisting of a sulfonic acid, a phosphonic acid, formic acid, acetic acid, propionic acid, oxalic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, lactic acid, tartaric acid, malic acid, phthalic acid, benzene tricarboxylic acid, 1,4-cyclohexanedicarboxylic acid and sebacic acid with a photoresist composition comprising a polymeric binder, a photoactive component, and optionally a cross-linking agent, wherein the organic acid is non-polymerizable with the polymeric binder, optional cross-linking agent or both, and is present in an amount of from 0.5 to 5 parts per 40 parts of polymeric binder on a dry weight basis.

13. (Currently Amended): The method of claim 12 wherein the organic acid is selected from the group consisting of ~~carboxylic acids and a sulfonic acids~~ acid, formic acid, acetic acid, propionic acid, oxalic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, lactic acid, tartaric acid, malic acid, phthalic acid, benzene tricarboxylic acid, salicylic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid and sebacic acid.

14. (Cancelled),

15. (Cancelled).

16. (Currently Amended). The method of claim ~~[[15]]~~ 13 wherein the organic acid is selected from the group consisting of acetic acid, propionic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, lactic acid, tartaric acid, ~~citric acid~~, malic acid, phthalic acid, benzene tricarboxylic acid, salicylic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid and sebacic acid.

17. (Original): The method of claim 12 wherein the photoresist is negative-acting.

18. (Currently Amended): A method of manufacturing a printed wiring board comprising the steps of a) disposing on a printed wiring board substrate a photoresist composition comprising a polymeric binder, a photoactive component, an organic acid selected from the group consisting of a sulfonic acid, a phosphonic acid, formic acid, acetic acid, propionic acid, oxalic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, phthalic acid, benzene

tricarboxylic acid, salicylic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid and sebacic acid and optionally a cross-linking agent, wherein the organic acid is non-polymerizable with the polymeric binder and optional cross-linking agent, and is present in an amount of from 0.5 to 5 parts per 40 parts polymeric binder on a dry weight basis; b) imaging the photoresist; and c) developing the photoresist.

19. (Currently Amended): The method of claim 18 wherein the organic acid is selected from the group consisting of ~~alkanecarboxylic acids, arylcarboxylic acids, alkanesulfonic acids, and amine carboxylic acids~~ a sulfonic acid, formic acid, acetic acid, propionic acid, oxalic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, lactic acid, tartaric acid, malic acid, phthalic acid, benzene tricarboxylic acid, salicylic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid and sebacic acid.

20. (Currently Amended): The method of claim 19 wherein the organic acid is selected from the group consisting of ~~(C<sub>1</sub>-C<sub>12</sub>)alkylcarboxylic acids, (C<sub>1</sub>-C<sub>12</sub>)alkyldicarboxylic acids, (C<sub>1</sub>-C<sub>12</sub>)alkyltricarboxylic acids, substituted (C<sub>1</sub>-C<sub>12</sub>)alkylcarboxylic acids, substituted (C<sub>1</sub>-C<sub>12</sub>)alkyldicarboxylic acids, substituted (C<sub>1</sub>-C<sub>12</sub>)alkyltricarboxylic acids, aryldicarboxylic acids and substituted arylcarboxylic acids~~ acetic acid, propionic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, lactic acid, tartaric acid, malic acid, phthalic acid, benzenetricarboxylic acid, salicylic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid and sebacic acid.